

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-2 (Canceled).

Claim 3 (Previously Presented): The resin-forming mold set forth in claim 16 or 17, wherein the electroconductive film comprises the aluminum and the at least one electroconductive metal in a weight ratio of 70:30 to 10:90.

Claim 4 (Previously Presented): The resin-forming mold set forth in claim 16 or 17, wherein said electroconductive film is formed by vapor deposition.

Claim 5 (Previously Presented): The resin-forming mold set forth in claim 16 or 17, wherein a thickness of the electroconductive film is 200 to 3000Å.

Claim 6 (Previously Presented): The resin-forming mold set forth in claim 16 or 17, wherein a ratio of the aluminum and the at least one electroconductive metal is 97.5:2.5 to 10:90 in terms of a molar ratio in a depth range of 10 to 100Å from the front face of the electroconductive film.

Claim 7 (Previously Presented): The resin-forming mold set forth in claim 16 or 17, wherein the concentration of aluminum monotonically decreases beginning at a depth area of 110 Å or more from the front face of the electroconductive film.

Claim 8 (Previously Presented): The resin-forming mold set forth in claim 17, wherein at least part of the aluminum forms an oxide of aluminum through reacting with said oxygen.

Claim 9 (Previously Presented): The resin-forming mold set forth in claim 16 or 17, wherein the at least one electroconductive metal is nickel.

Claim 10 (Previously Presented): The resin-forming mold set forth in claim 16 or 17, wherein the electroformed layer is a nickel-electroformed layer formed of nickel.

Claim 11 (Previously Presented): A method for producing a resin-forming mold, comprising:

fitting aluminum to a heating heat generator inside a vacuum deposition apparatus, leaving a predetermined amount of the aluminum on the heat generator by partially evaporating away the aluminum fitted to the heating heat generator, fitting a master plate comprising a substrate and a photoresist film on the substrate to a substrate holder inside said vacuum deposition apparatus, said photoresist film being adapted to form a predetermined uneven pattern and fitting at least one electroconductive metal on said heating heat generator;

forming an electroconductive film on the photoresist film of the master plate by vacuum depositing the left aluminum and the at least one electroconductive metal on the heating heat generator;

forming an electroformed layer on the electroconductive film by electroforming at least one electroforming metal; and

obtaining the resin-forming mold by removing the master plate from the electroconductive film.

Claim 12 (Previously Presented): The method for producing the resin-forming mold set forth in claim 11, wherein a weight ratio between the left aluminum and the fitted electroconductive metal is in a range of 90:10 to 10:90.

Claim 13 (Previously Presented): The method for producing the resin-forming mold set forth in claim 11, wherein a thickness of the electroconductive film is 200 to 3000Å.

Claim 14 (Previously Presented): The method for producing the resin-forming mold set forth in claim 11, wherein the at least one electroconductive metal is nickel.

Claim 15 (Previously Presented): The method for producing the resin-forming mold set forth in claim 11, wherein the at least one electroforming metal is nickel.

Claim 16 (Currently Amended): A resin-forming mold comprising an electroformed layer, and an electroconductive film having a front face and a back face, on said electroformed layer, wherein said electroconductive film has uneven portions formed on said front face thereof and said electroformed layer is formed on said back face, wherein said front face is substantially formed of aluminum and said back face is formed of at least one electroconductive metal, wherein an intermediate portion of said electroconductive film from the front face to the back face comprises aluminum and said at least one electroconductive metal, and wherein a compounding ratio between said aluminum and said at least one electroconductive metal continuously changes from the front face toward the back face, ~~and wherein a surface layer of the electroconductive film is not peeled when a resin molded body is formed from a resin using said resin-forming mold and then released from the mold.~~

Claim 17 (Currently Amended): A resin-forming mold comprising an electroformed layer, and an electroconductive film having a front face and a back face, on said electroformed layer, wherein said electroconductive film has uneven portions formed on said front face thereof and said electroformed layer is formed on said back face, wherein said front face is substantially formed of aluminum and oxygen, and said back face is formed of at least one electroconductive metal, wherein an intermediate portion of said electroconductive film from the front face to the back face comprises aluminum and said at least one electroconductive metal, and wherein a compounding ratio between said aluminum and said at least one electroconductive metal continuously changes from the front face toward the back face, ~~and wherein a surface layer of the electroconductive film is not peeled when a resin molded body is formed from a resin using said resin-forming mold and then released from the mold.~~

DISCUSSION OF THE AMENDMENT

Claims 16 and 17 have each amended by deleting the phrase “ and wherein a surface layer of the electroconductive film is not peeled when a resin molded body is formed from a resin using said resin-forming mold and then released from the mold.”

No new matter is believed to have been added by the above amendment. Claims 3-17 remain pending in the application.